

STPS60H100C

Power Schottky rectifier

Main product characteristics

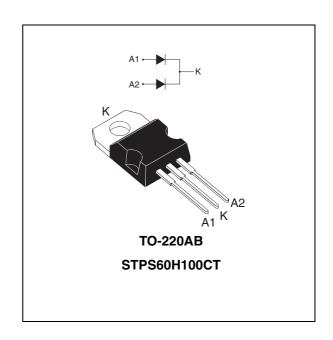
I _{F(AV)}	2 x 30 A
V _{RRM}	100 V
Tj	175° C
V _{F(max)}	0.72 V

Feature and benefits

- High junction temperature capability
- Low leakage current
- Low thermal resistance
- High frequency operation
- Avalanche specification

Description

Dual center tab Schottky rectifier suited for High Frequency server and telecom base station SMPS. Packaged in TO-220AB, this device combines high current rating and low volume to enhance both reliability and power density of the application.



Order code

Part Number	Marking
STPS60H100CT	STPS60H100CT

Table 1. Absolute ratings (limiting values)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			100	V
I _{F(RMS)}	RMS forward current			60	Α
I _{F(AV)}	Average forward current		Per diode Per device	30 60	А
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms Sinusoidal}$			300	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \ \mu s \ T_j = 25^{\circ} \ C$			18100	W
T _{stg}	Storage temperature range			-65 to + 175	° C
Tj	Maximum operating junction temperature ⁽¹⁾			175	° C
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs

^{1.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Characteristics STPS60H100C

1 Characteristics

Table 2. Thermal resistances

Symbol	Parameter		Value	Unit
R _{th(j-c)}	Junction to case	Per diode Total	1.0 0.7	° C/W
R _{th(c)}		Coupling	0.4	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_j(diode 1) = P(diode 1) \times R_{th(j-c)}(per diode) + P(diode 2) \times R_{th(c)}$

Table 3. Static electrical characteristics (per diode)

Symbol	Test conditions			Min.	Тур.	Max.	Unit
ı (1) D	I _R ⁽¹⁾ Reverse leakage current	T _j = 25° C	$V_R = V_{RRM}$		2	10	μΑ
'R'		T _j = 125° C			3	10	mA
	V _F ⁽²⁾ Forward voltage drop	T _j = 25° C	I _F = 30 A			0.84	
V_(2)		T _j = 125° C	I _F = 30 A		0.67	0.72	V
VF.		T _j = 25° C	I _F = 60 A		0.92	0.98	V
		T _j = 125° C	I _F = 60 A		0.8	0.84	

^{1.} Pulse test : tp = 5 ms, δ < 2%

To evaluate the maximum conduction losses use the following equation :

$$P = 0.6 \times I_{F(AV)} + 0.004 IF^{2}_{(RMS)}$$

^{2.} Pulse test : tp = 380 μ s, δ < 2%

STPS60H100C Characteristics

Figure 1. Average forward power dissipation versus average forward current (per diode) Figure 2. Average forward current versus ambient temperature (δ = 0.5, per diode)

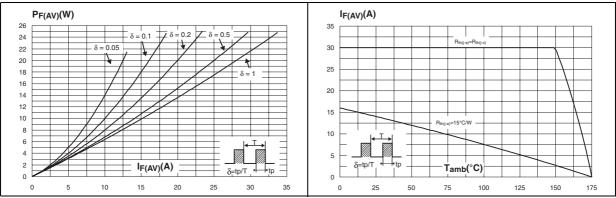


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

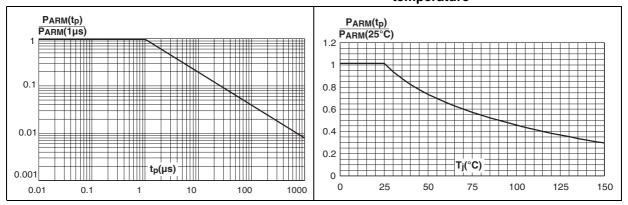
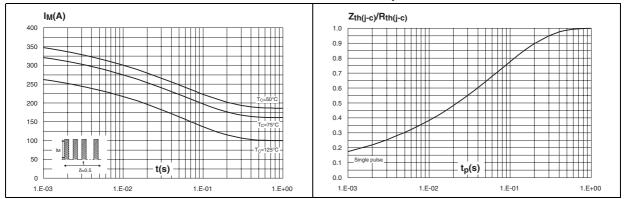


Figure 5. Non repetitive surge peak forward current versus overload duration

Figure 6. Relative variation of thermal impedance junction to case versus pulse

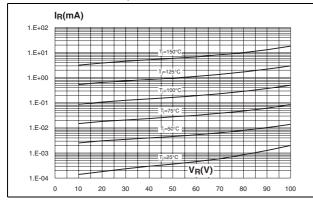


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Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

Figure 8. Junction capacitance versus reverse voltage applied (typical values)



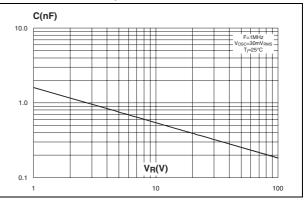
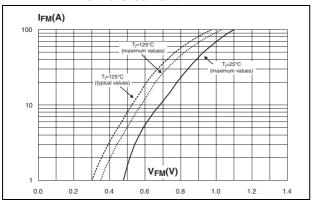


Figure 9. Forward voltage drop versus forward current



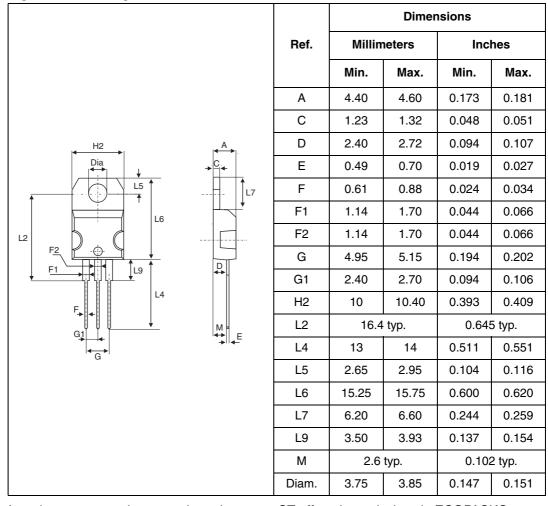
STPS60H100C Package information

2 Package information

Epoxy meets UL94, V0

Cooling method: by conduction (C)
 Recommended torque value: 0.8 Nm
 Maximum torque value: 1.0 Nm

Figure 10. Package dimensions TO-220AB



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

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Ordering information STPS60H100C

3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS60H100CT	STPS60H100CT	TO-220AB	2.20 g	50	Tube

4 Revision history

Date	Revision	Description of Changes
02-Aug-2004	1	First issue
07-Feb-2007	2	Reformatted to current stndards. Added ECOPACK statement on page 5. Corrected typograhical errors on pages 1 and 3

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